PCN Number:	20	20140702000 PCN Date: 07/07/2014										
Title: Qualification	of C	of Carsem as an alternate Assembly/Test site for the TPS25200DRVR/T										
Customer Contact:	PCN Manager			P	Phone: +1(214)480-6037			037	Dept: Quality Services			
Proposed 1 st Ship Da	1st Ship Date: 10/07/20				14 Estimated Sample Avai				lability: Date provided upon request			
Change Type:												
Assembly Site		Assembly I			Process 🛛 🖾 As				ssembly Materials			
Design		Electrical Specification Mechanical Specificatio							ication			
Test Site		Packing/Shipping/Labeling Test Process										
Wafer Bump Site									Vafer Bump Process			
Wafer Fab Site			Wafer Fa					Waf	Wafer Fab Process			
			Part num									
PCN Details												
Description of Change	je:											
Texas Instruments is pleased to announce the qualification of Carsem Suzhou as an additional Assembly and test site for the TPS25200DRVR/T. Material differences are noted below.												
			TI C	lark AT			Carsem					
Mount Compound					420)7768			435143			
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ. Reason for Change: Continuity of Complex												
Continuity of Supply										_		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):												
None Changes to product identification resulting from this PCN:												
Assembly Site												
TI Clark	, ,									O: QAB		
Carsem Assembly Site Origin (22L) ASO: CSZ								O: CSZ				
Sample product shipping label (not actual product label)												
MADE IN: Malaysia G4 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT G3/29/04 MSL 1 /235C/UNLIM 03/29/04 G3/29/04 OPT: 39 LTEM: 39 LBL: 5A (L)T0:1750 (L)T0:1750												
Topside Device marking : Assembly site code for QAB= I Assembly site code for CSZ= F												

Product Affected									
TPS25200DRVR TPS25200DRVT									
Quali	ficat	tion Data – A	oproved June,	20	14				
This qualification has been sp	ecifica	ally developed for th	e validation of this c	hang	e. T				
validates that the pro							ns.		
Qualific			5200DRV (MSL	2-26	0C)				
Package Construction Details									
Assembly Site:	CSZ	SZ Mount Compou							
# Pins-Designator, Family:	6-DF	RV, WSON	Mold Compound:			SID#441086			
Lead frame (Finish, Base):	NiPd	iPdAu, Cu Bond W				: 2.0 Mil Dia., Cu			
Qualification: 🗌 Plan	<u> </u>	est Results							
Reliability Test	C	Conditions				Sample Size/Fail			
High Temp Operating Life	1	150C (300 Hrs)				77/0			
Electrical Characterization	F	Per Datasheet	Pass						
**T/C -65C/150C	-	-65C/+150C (500	77/0						
ESD CDM	-	+/- 500V				3/0			
ESD HBM	-	+/- 500V, 1000V				3/0			
Latch-up		Per JESD78				6/0			
Notes **- Preconditioning	seque	ence: Level 1-260	С.						
Qualifica	atio	n Data - Appro	oved January,	20	13				
This qualification has been de		•							
will validate that the proposed change meets the applicable released technical specifications.									
Reference Qua			010017RSAR2 (M	1SL2	-26	0C)			
Package Construction Details									
Assembly S						#435143			
# Pins-Designator, Fam Leadframe (Finish, Bas									
Qualification: Plan		Test Results				™III Dia.,	Cu		
	$\overline{}$			S	amr	ole Size	/ Fail		
Reliability Test	onditions	ditions				Lot#3			
Electrical Characterization	Sid	Side by side				Lot#2	-		
**High Temp. Storage Bake				Pa 77		77/0	77/0		
**Autoclave 121C		121C, 2 atm (96 Hrs)				77/0	77/0		
**T/C -65C/150C		-65C/+150C (500 Cyc)				77/0	77/0		
Notes: ** Tests require prec		· · ·	, ,	77					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com